



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 6334**  
Koji MISHIMA et al. : Attorney Docket No. 2003\_1305  
Serial No. 10/660,483 : Group Art Unit 1742  
Filed September 12, 2003 : Examiner William T. Leader

METHOD AND APPARATUS FOR PLATING  
SUBSTRATE WITH COPPER

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PATENT TO DEPOSIT  
ACCOUNT NO. 23-0875

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**AMENDMENT AFTER FINAL**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

RESPONSE UNDER 37.CFR1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 1742

Sir:

Responsive to the Office Action dated September 22, 2006, please amend the  
above-identified application as follows.